



Fig. 2 is a perspective view of a multi-layered printed circuit board assembly 300. The assembly 300 includes a plurality of layers 310, which are stacked on top of each other. Each layer 310 has a plurality of vias 370, which are formed in the layers 310. The vias 370 are used to connect the layers 310 to each other. The assembly 300 also includes a plurality of conductive traces 310, which are formed on the layers 310. The traces 310 are used to connect the vias 370 to each other. The assembly 300 is shown in a perspective view, with the layers 310 and vias 370 clearly visible.

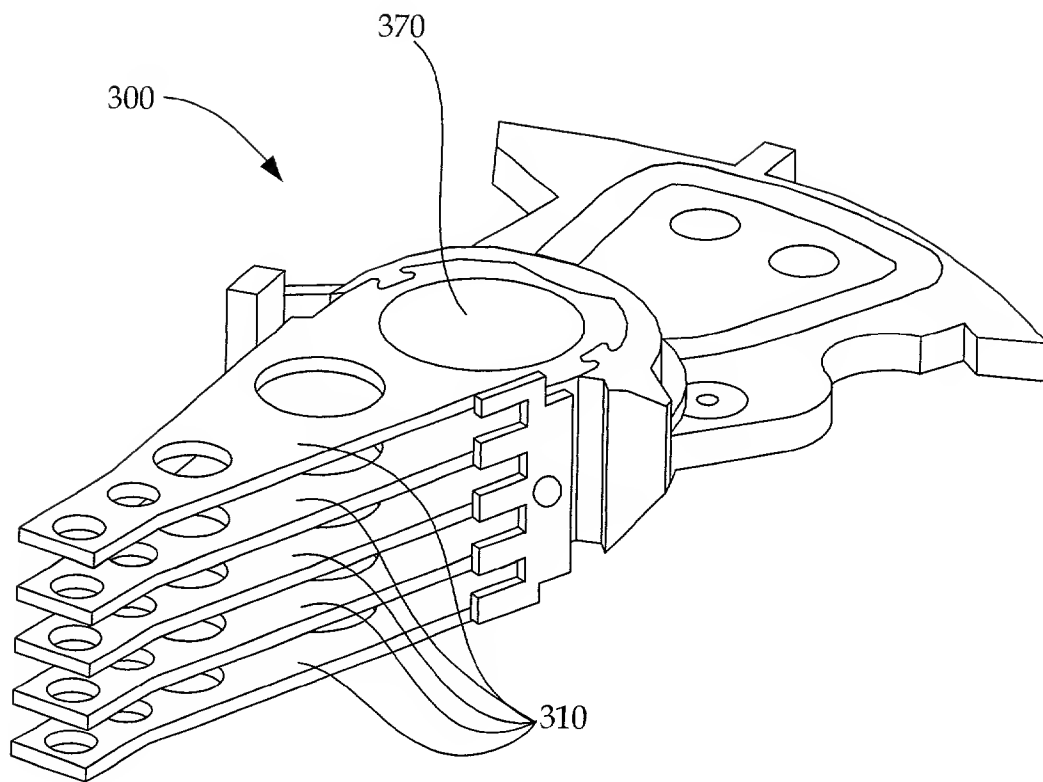


Fig. 2

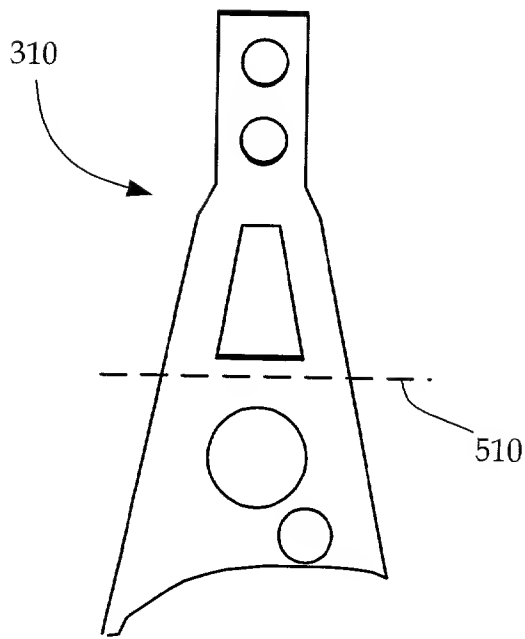


Fig. 3

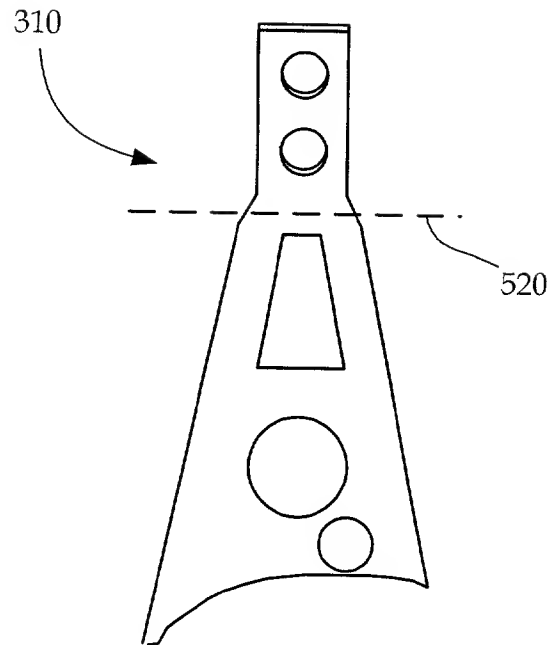


Fig. 4

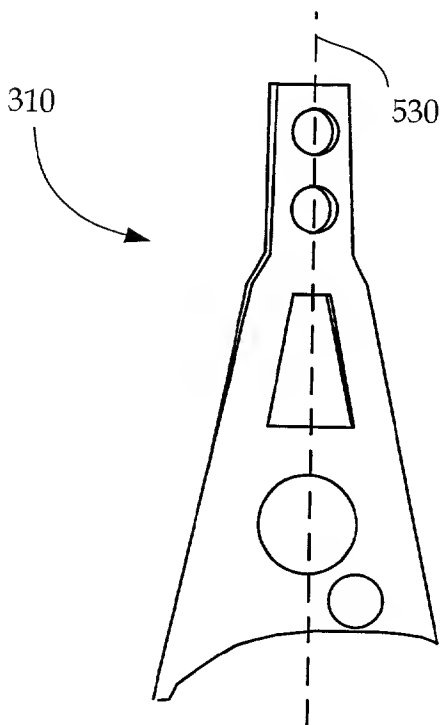


Fig. 5

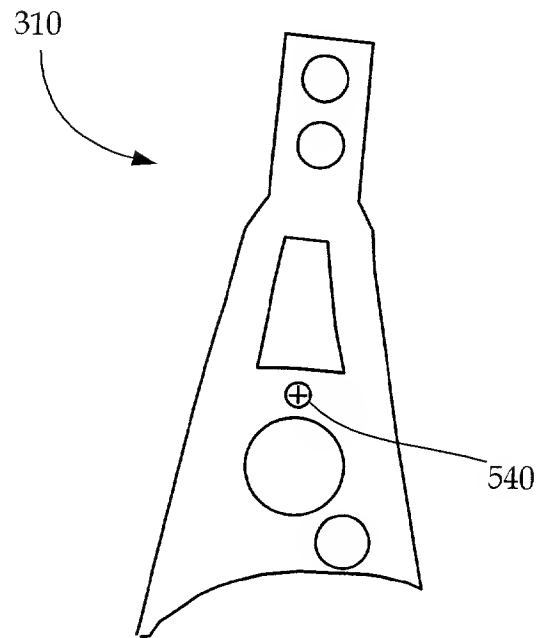


Fig. 6

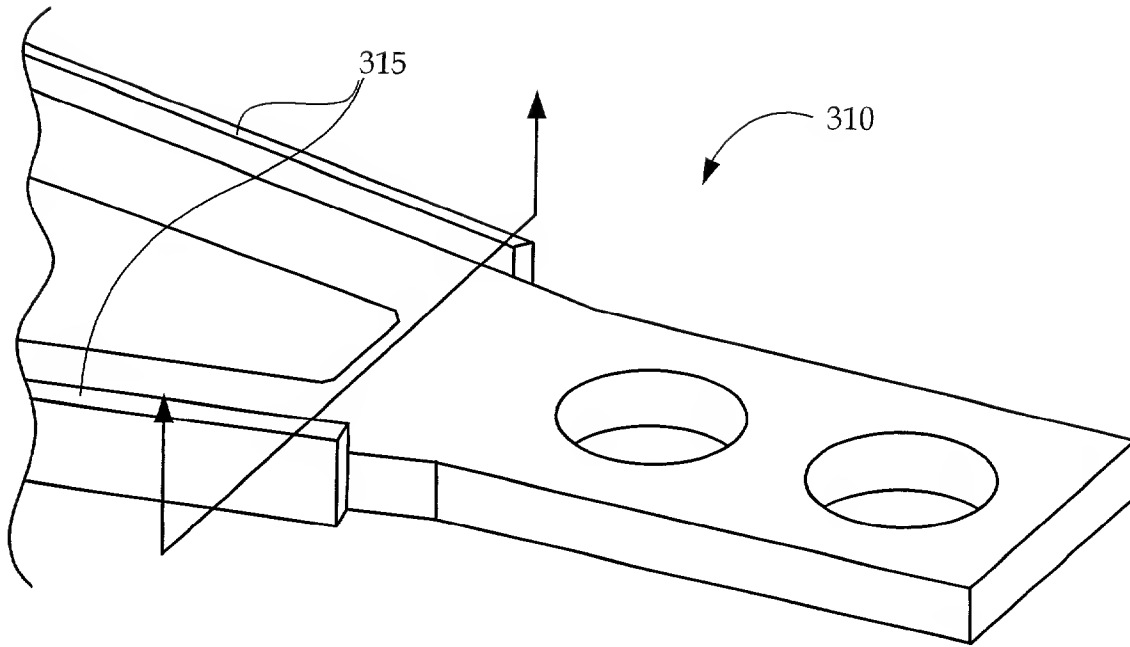


Fig. 7

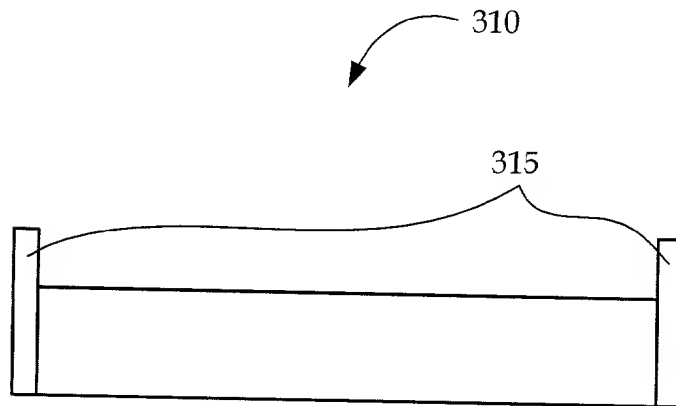


Fig. 8